

## AMENDMENTS TO THE CLAIMS

*Please cancel claims 6 and 14 without prejudice.*

*Please amend the claims as follows:*

1. (Currently amended) A flip chip package comprising:
  - a chip, the chip comprising a top surface, a bottom surface and one or more side surfaces disposed between the top and bottom surfaces;
  - a substrate, the substrate comprising an upper surface;
  - a plurality of reflowed solder bumps, the reflowed solder bumps electrically coupling the top surface of the chip with an adjacent portion of the upper surface of the substrate; and

a monolithic element comprising solidified resin, the monolithic element resulting from a single molding process, the monolithic element encapsulating and adhesively bonded to (i) substantially all of the one or more side surfaces, (ii) a substantial portion of the upper surface, and (iii) the plurality of reflowed solder bumps located in a gap between the top surface of the chip and the upper surface of the substrate, the monolithic element including a removable portion on the upper surface of the substrate resulting from a runner used to inject the resin in the single molding process.
2. (Currently amended) The flip chip package of claim 1, wherein the solidified resin does not encapsulate the bottom surface of the chip.

3. (Original) The flip chip package of claim 2, wherein the resin further comprises a filler material.
4. (Original) The flip chip package of claim 3, wherein the filler material comprises silica microspheres.
5. (Currently amended) The flip chip package of claim 1, wherein the resin encapsulates substantially all of the one or more side surfaces of the chip.
6. (Cancelled)
7. (Original) The flip chip package of the claim 1, wherein the solidified resin comprises an epoxy.
8. (Original) The flip chip package of claim 1, wherein the substrate is a thin substrate.
9. (Original) The flip chip package of claim 1, wherein the substrate is comprised of a polymeric material.
10. (Currently amended) The flip chip package of claim 8, wherein the substrate is approximately between 0.05mm to and 0.5mm thick in thickness.
11. (Original) The flip chip package of claim 1, further comprising at least one passive component electrically coupled with the substrate.
12. (Original) The flip chip package of claim 11, wherein the solidified resin fills a gap between a first surface of the at least one passive component and an adjacent surface of the substrate.

13. (Original) The flip chip package of claim 11, wherein the solidified resin fully encapsulates the at least one passive component.
14. (Cancelled)
15. (Currently amended) A microelectronic device comprising:
  - a substrate comprising a first surface;
  - a chip comprising a first surface, a second surface, and one or more edges, the first surface being coupled with the first surface of the substrate by a plurality of solder bumps, the solder bumps providing electrical connection between the chip and the substrate; and
  - a solid resin element, the solid resin element resulting from a process of injecting liquid resin into a mold containing the chip and substrate in a single molding process, the solid resin element encapsulating and bonding to the first surface of the chip, the one or more edges of the chip, the first surface of the substrate, and the plurality of solder bumps, the solid resin element including a removable portion on the first surface of the substrate resulting from injection of the resin through a runner during the molding process.
16. (Previously presented) The microelectronic device of claim 15, wherein the solid resin is not bonded with a second surface of the chip.
17. (Previously presented) The microelectronic device of claim 16, wherein the second surface of the chip was in contact with the mold during the process of injecting liquid resin into the mold.

18. (Previously presented) The microelectronic device of claim 15, wherein the resin further comprises a filler material.
19. (Previously presented) The microelectronic device of claim 18, wherein the filler material comprises microspheres or microballoons.
20. (Previously presented) The microelectronic device of claim 19, wherein the microspheres or microballoons are comprised of silica.
21. (Previously presented) The microelectronic device of claim 19, wherein the microspheres or microballoons are comprised of glass.
22. (Previously presented) The microelectronic device of claim 19, wherein the resin comprises an epoxy.